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HEET

To the Honorable Commissioner

ginal documents or copy thereof.

1. Name of conveying part(ies):

Juen-Kuen Lin, Chien-Hsin Lai, Hao-Kuang Chiu, and Fu-Yang Yu

Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies)

Name: United Microelectronics Corp.  
Street Address: No. 3, Li-Hsin Rd. II., Science-Based Industrial Park, Hsinchu City, Taiwan, R.O.C.

Name: United Semiconductor Corp.  
Street Address: No. 3, Li-Hsin Rd. II., Science-Based Industrial Park, Hsinchu City, Taiwan, R.O.C.

Additional name(s) & address(es) attached?  Yes  No

3. Nature of conveyance:

- Assignment
- Security Agreement
- Other:
- Merger
- Change of Name

Execution Date: September 28, 1999, September 28, 1999, September 28, 1999, and September 29, 1999

jc564 U.S. PTO  
09/420961  
10/20/99

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: September 28, 1999, September 28, 1999, September 28, 1999, and September 29, 1999

*09/420961*

A. Patent application No.(s)

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Daniel R. McClure  
Thomas, Kayden, Horstemeyer & Risley, L.L.P.  
100 Galleria Parkway, Suite 1500  
Atlanta, Georgia 30339

6. Total number of applications/patents involved: [ 1 ]

7. Total fee (37 CFR 3.41) \$ 40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit Account Number:

20-0778

(Attach duplicate copy of this page if paying by Deposit Account)

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9. Statement and signature. *To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Type Name of Person Signing - Daniel R. McClure

Date

Docket # 252103-4240

Total number of pages including cover sheet, attachments, and document: [ 3 ]

Mail documents to be recorded with required cover sheet information to:  
Assistant Commissioner for Patents, Box Assignments  
Washington, D.C. 20231

# ASSIGNMENT

WHEREAS, 1. Juen-Kuen Lin  
3. Hao-Kuang Chiu

2. Chien-Hsin Lai  
4. Fu-Yang Yu

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **METHOD TO MAINTAIN CONSISTENT THICKNESS OF THIN FILM  
DEPOSITED BY CHEMICAL VAPOR DEPOSITION**

Filed: Serial No.

Executed concurrently with the execution of this instrument

WHEREAS, 1. United Microelectronics Corp., of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.  
2. United Semiconductor Corp., of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

# ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Juen-Kuen Lin  
Signature:

Sole or First Joint Inventor: Juen-Kuen Lin

1999-9-28  
Date:

Chien-Hsin Lai  
Signature:

Second Joint Inventor (if any): Chien-Hsin Lai

1999-9-28  
Date:

Hao-Kuang Chiu  
Signature:

Third Joint Inventor (if any): Hao-Kuang Chiu

1999.9.28  
Date:

Fu-Yang Yu  
Signature:

Fourth Joint Inventor (if any): Fu-Yang Yu

1999:9.29  
Date: